The MOSFET drain to source current threshold is: \( I_{DSTH} = \frac{V_{DS} \times I_{SENSE}}{R_{DSON}} \)

Vin\(_{MAX}\) = OVP\(_{th}\) + \(\frac{R_2 \times OVP_{th}}{R_3}\)

\( R_2 = R_3 \times (Vin_{MAX} - OVP_{th}) / OVP_{th} \)

If OVP not used, DO NOT Populate R2, R3 short to ground

\( R_{UVLO} = \frac{Vin_{(min)} - UVLO_{TH}}{UVLO_{bias} + (UVLO_{TH}/R_{OPT})} \)

DO NOT Populate R\(_{OPT}\) IF UVLO NOT USED

The MOSFET drain to source current threshold is: \( I_{DSTH} = I_{SENSE} \times \frac{V_{DS}}{R_{DSON}} \)
PCB Number: PMP10748   
PCB Rev: E1  
PCB LOGO  
Texas Instruments  
Pb-Free Symbol

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
</tr>
</thead>
<tbody>
<tr>
<td>001</td>
<td>UVLO Optional</td>
</tr>
</tbody>
</table>

**Assembly Notes**

**ZZ2**  
These assemblies are ESD sensitive, ESD precautions shall be observed.

**ZZ3**  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

**ZZ4**  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
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